



# OL-PMCM6501VPE

WLCSP6: wafer level chip-size package; 6 bumps (3 x 2)

7 June 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP6
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Package body material type</b>	X (other)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-7-2015
<b>Manufacturer package code</b>	WLCSP6

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.45	-	1.48	1.51	mm
E	package width	0.95	-	0.98	1.01	mm
A	seated height	0.315	-	0.345	0.375	mm
A <sub>2</sub>	package height	0.13	-	0.145	0.16	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	6	-	

## 2. Package outline

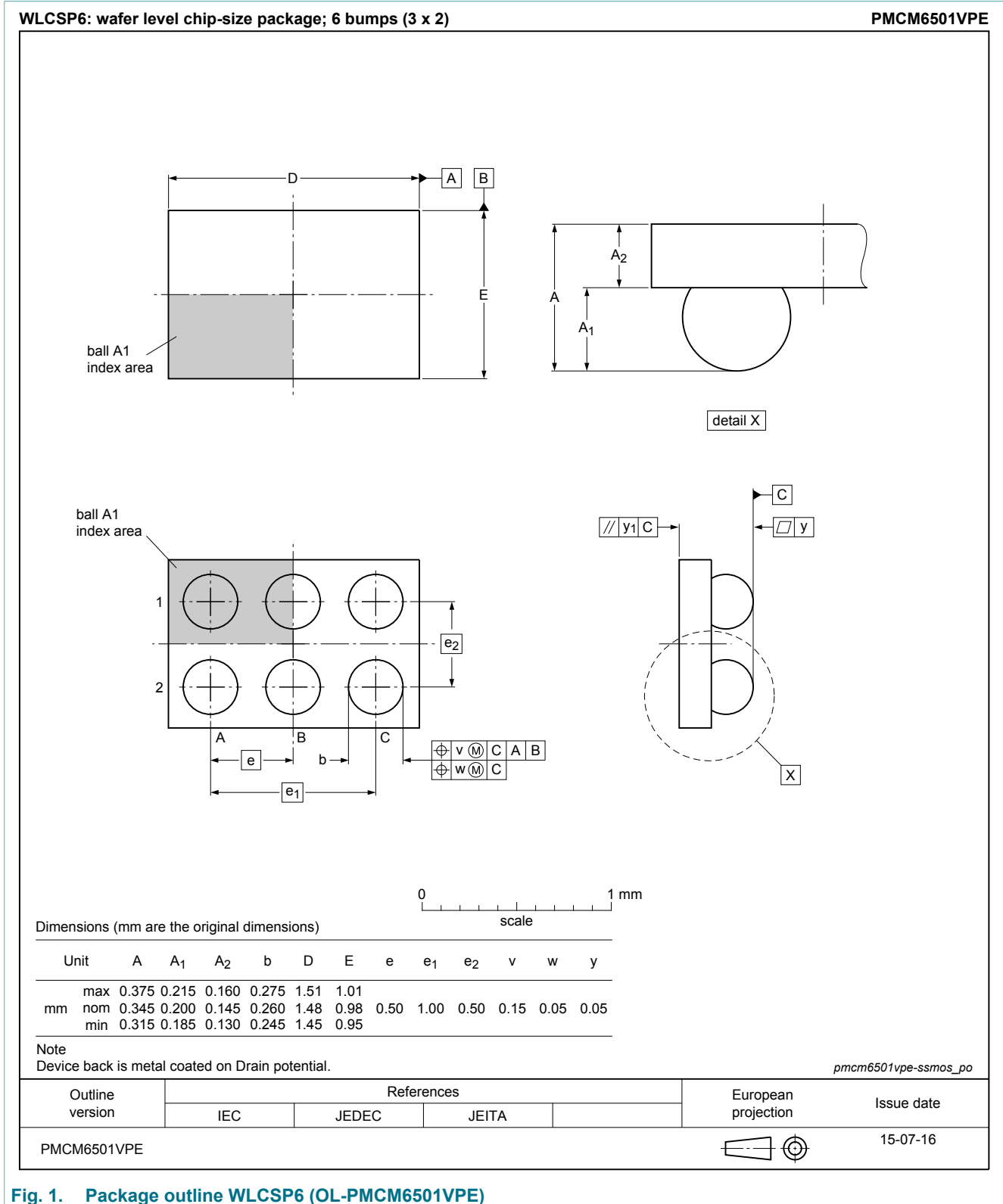


Fig. 1. Package outline WLCSP6 (OL-PMCM6501VPE)

### 3. Soldering

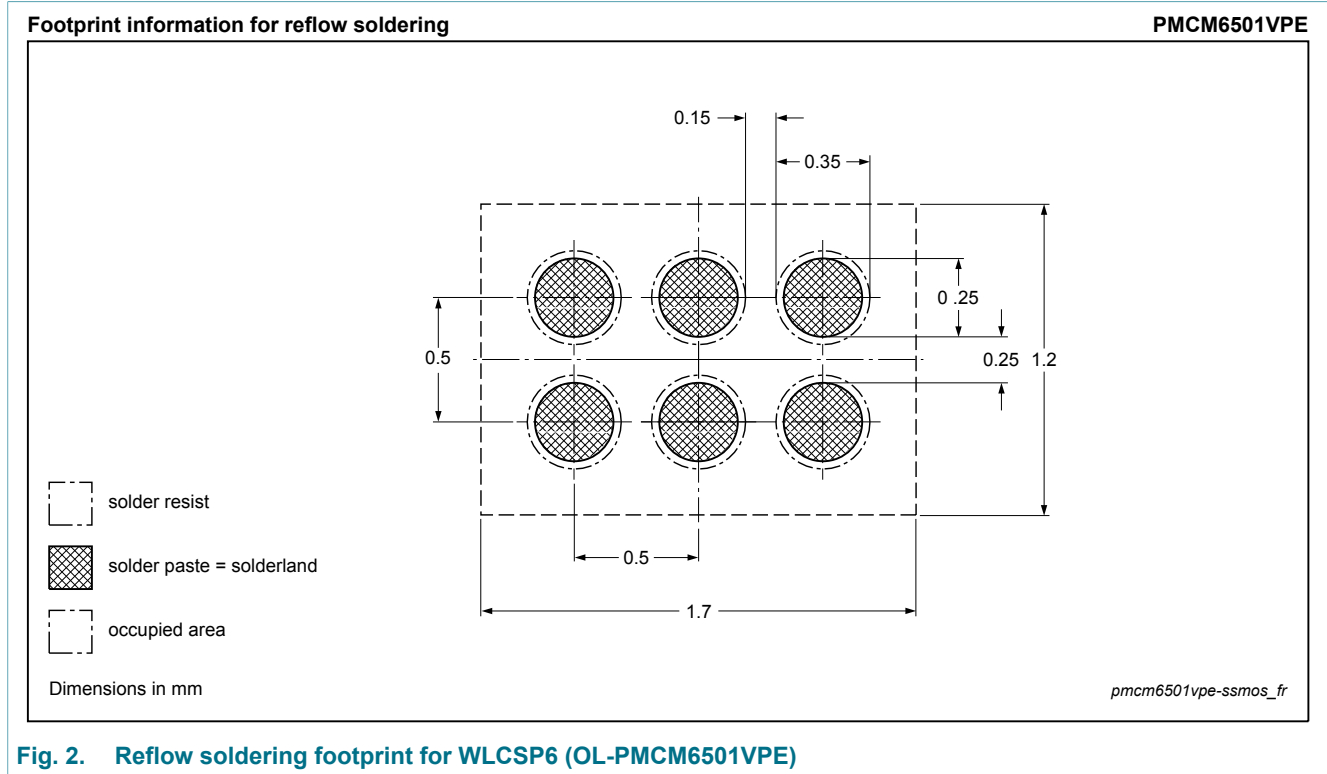


Fig. 2. Reflow soldering footprint for WLCSP6 (OL-PMCM6501VPE)

## 4. Legal information

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